Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	91	substrate and (first adj chip) and (second adj chip) and (package or packaging) and (bump or bumps) and (encapsulat\$4)	USPAT	OR	OFF	2005/01/04 13:41
L2	84	substrate and (first adj chip) and (second adj chip) and (package or packaging) and (bump or bumps) and (encapsulat\$4)	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	OFF	2005/01/04 13:41